

QMFF300R17EFF

1700V 300A IGBT Module

Electrical Features

- Trench/Fieldstop IGBT
- Half-bridge
- Standard package
- High short circuit capability
- Including anti-parallel FWD



Typical Applications

- Frequency converter
- UPS
- High Power Converters
- Motor Drives
- Wind Turbines

IGBT, Inverter

Maximu	m Rated Values						
Symbol	Item	Conditions			Rating		Unit
IGBT							
V _{CES}	Collector-emitter voltage	T_{vj} =25°C			1700		V
V_{GES}	Gate-emitter voltage	-			±20		V
$I_{\rm C}$	Collector current,DC	$T_{C}=100^{\circ}\text{C}, T_{\text{vj}}=175^{\circ}$	°C		300		A
I _{CRM}	Repetitive peak collector current	$t_p=1$ ms			600		A
t_{SC}	Short circuit withstand time	$V_{GE}=15V, V_{CC}=800V, T_{vj}\leq 150^{\circ}C$			10		us
P _{tot}	Total power dissipation	T _C =25°C,T _{vj} =175°C			1807		W
Characte	eristics Values						
Symbol	Item	Conditions			Values		Unit
IGBT				Min.	Тур.	Max.	
I _{CES}	Collector-emitter cut-off current	$V_{CE}=1700V, V_{GE}=0$	V _{CE} =1700V,V _{GE} =0V,T _{vj} =25°C		-	1	mA
I _{GES}	Gate leakage current	V _{CE} =0V,V _{GE} =20V,T _{vj} =25°C		-	-	250	nA
$V_{\text{GE(th)}}$	Gate-emitter threshold voltage	$I_C=12\text{mA}, V_{CE}=V_{GE}, T_{vj}=25^{\circ}\text{C}$		5.2	5.68	6.5	
	Collector-emitter saturation voltage	I _C =300A	T _{vj} =25°C	11,50	1.95	-	$\frac{1}{V}$
V _{CEsat}		$V_{GE}=15V$	T _{vj} =125°C		-		
		v GE-13 v	T _{vj} =150°C	-	-	-	
Cies	Input capacitance	- V _{CE} =25V,V _{GE} =0V - f=1MHz,T _{vj} =25°C		-	29.2	-	
Coes	Output capacitance			-	0.98	-	nF
Cres	Reverse transfer capacitance			-	0.88	-	
Q _G	Gate charge	V _{CC} =900V, I _C =300A, V _{GE} =15V		-	3.4	-	uС
$R_{\rm g}$	Internal gate resistance	$T_{vj}=25^{\circ}C$		-	2	-	Ω



$t_{d(on)}$			T _{vj} =25°C	-	309	-	-
	Turn-on delay time		$T_{vj}=125$ °C	-	-	-	
			T _{vj} =150°C	-	-	-	
			T _{vj} =25°C	-	125	-	
t_r	Rise time		$T_{vj}=125$ °C	-	-	-	
			T _{vj} =150°C	-	-	-]
$t_{ m d(off)}$		$V_{\text{CC}}=900\text{V},$	T _{vj} =25°C	-	489	-	ns
	Turn-off delay time	$I_{C}=300A,$	T _{vj} =125°C	-	-	-	
		$V_{GE}=\pm 15V$,	T _{vj} =150°C	-	-	_]
		$R_{G(on)}=2.4 \Omega$,	T _{vj} =25°C	-	384	-	
$t_{\rm f}$	Fall time	$R_{G(off)}=2.4 \Omega$,	T _{vj} =125°C	-	-	_	
		Inductive load	T _{vj} =150°C	-	-	-	
			T _{vj} =25°C	-	70.5	-	
E_{on}	Turn-on energy (per pulse)		$T_{vj}=125$ °C	-	-	-	1
			T _{vj} =150°C	-	-	-	1
			$T_{vj}=25^{\circ}C$	-	62.4	-	mJ
E_{off}	Turn-off energy (per pulse)		T_{vj} =125°C	-	-	_	1
			T _{vj} =150°C	_	-	_	1
R _{thJC}	Thermal resistance, junction to case	per IGBT		-	-	0.083	K/W
R _{thCH}	Thermalresistance, case to heatsink		per IGBT/ λgrease=1W/(m·K)		0.033	_	K/W
	Temperature under switching		,				
T_{vjop}	conditions			-40		150	°C
Diode,	Inverter				1		1
Maximu	m Rated Values						
Symbol	Item	Con	Conditions			ting	Unit
V_{RRM}	Repetitive peak reverse voltage	T _{vj} =25°C			17	700	V
I_{F}	Forward current,DC				300		A
I _{FRM}	Repetitive peak forward current	t _p =1ms			60	A	
	eristic Values	1 *			1		
		T 2001	T _{vj} =25°C	-	1.85	_	
$V_{\rm F}$	Continuous forward voltage	I _F =300A	T _{vi} =125°C	-	-	- V	V
•		$V_{GE}=0V$	T _{vj} =150°C	-	-	_	1
			T _{vj} =25°C	-	228	_	
I_{RM}	Peak reverse recovery current		T _{vj} =125°C	_	_	_	A
			T _{vj} =150°C	_	_	_	1
t_{rr}			$T_{vi}=25^{\circ}C$	_	522	_	
	Reverse recovery time	$V_R=900V$	$T_{vj}=125$ °C	-	_	_	ns
		$I_F=300A$	$T_{vj} = 150^{\circ}C$	_	_	_	1
Qr		$di_F/dt=-3531A/\mu s$	T_{vj} =25°C	_	43.3	_	
	Recovered charge	223111 pts	$T_{vj} = 125^{\circ}C$	_	-	_	μС
			$T_{vj} = 150^{\circ}C$	_	_	_	
		_	T_{vj} =150°C	_	26.8	_	
E_{rec}	Reverse recovery energy		T_{vj} =23°C	_	20.0	_	
∟ rec	reverse recovery energy		$T_{vj}=123 \text{ C}$ $T_{vj}=150 \text{ °C}$		-	_	1113
			1 vj-130 C	-	-	_	1



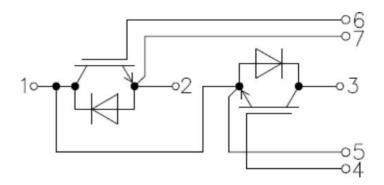
R _{thJC}	Thermal resistance, junction to case	per diode	-	-	0.13	K/W
R _{thCH}	Thermalresistance,case to heatsink	per diode/ λgrease=1W/(m·K)	-	0.051	-	K/W
$T_{ m vjop}$	Temperature under switching conditions		-40		150	°C

Module

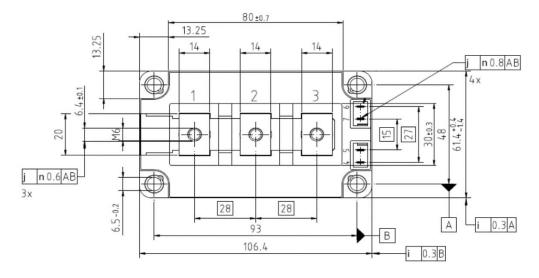
Module						
Symbol	Item	Conditions	Rating			Unit
V_{ISOL}	Isolation voltage	Terminals to baseplate, RMS,f=50Hz,t=1min		4000		V
-	Material of module baseplate	-		Cu		-
-	Internal isolation	Basic insulation(class 1, IEC 61140)	Al ₂ O ₃		-	
T_{stg}	Storage temperature	-	-40~125		°C	
Symbol	Item	C. Ivi	Valu		Values	
		Conditions	Min.	Тур.	Max.	
M	Mounting torque for module mounting	Screw M6	3.0	-	6.0	Nm
	Terminal connection torque	Screw M6	2.5	-	5.0	Nm
ds	Creepage distance	Terminal to terminal	-	23	-	
		Terminal to base plate	-	29	-	mm
da	Clearance	Terminal to terminal	-	11	-	
		Terminal to base plate	-	23	-	mm
m	Weight	-	-	315	-	g

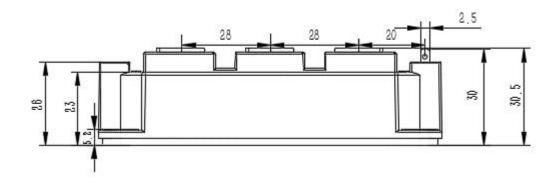


Circuit diagram headline



Package outlines (Unit: mm)







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